



NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH (1.5MICRON)MIN. THK. OVER 100 MICRO INCH (2.54 MICRON)NOM. THICKNESS OF NICKEL UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. FLATNESS PERTAINS METALLIZED PAD ONLY.
3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100 VDC.
4. NO PIN CONNECTED TO SEAL AREA AND DIE ATTACH PAD.

5. PART NO

PART NO.	HEAT SINK METALLIZATION		
01	WITHOUT	FC-24CNB	S=0
02	WITH	FC-24CA	D=0

MODIFICATIONS

MODIFICATIONS	DATE	DRAWN	CHECKED	APPROVED
ADD:TABLE,CHANGE: $\square .003 \rightarrow \square .002$	83.5.23	T.I	O.M	Y.S
CHANGED : NOTE:1 BONDING PAD SOLDER PAD $.060 \pm .006 \rightarrow .060 \pm .007$	79.8.25	N.U	O.M	
CHANGED : .020R REF. TYP. $\rightarrow$ .012R REF. TYP. MATERIAL				
CHANGED : $.294 \pm .006 \rightarrow .285 \pm .005$ .022MIN $\rightarrow$ .0175MIN	79.7.26	N.U	O.M	
CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 24 LEAD CHIP CARRIER

SCALE 10/1

MATERIAL KYOCERA A-440

**KYOCERA**

KYOCERA CORPORATION  
KYOTO JAPAN

TOLERANCES:  
UNLESS OTHERWISE SPECIFIED  
 $\pm 1\%$   
N.L.T  $\pm .005(0.13)$   
THIRD ANGLE PROJECTION

FCS-90387-C

DRAWN S.M	CHECKED UE	APPROVED K.H	DATE MAR.04.'99
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DRAWING NO. PB-92234-C

SHEET 1/1